DATA SHEET

74LVC273

Octal D-type flip-flop with reset; positive-edge trigger

Product specification Supersedes data of 1996 Jun 06 IC24 Data Handbook





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FEATURES

- Wide supply voltage range of 1.2V to 3.6V
- Conforms to JEDEC standard 8-1A
- Inputs accept voltages up to 5.5V
- CMOS low power consumption
- Direct interface with TTL levels
- Output drive capability 50Ω transmission lines @ 85°C

DESCRIPTION

The 74LVC273 is a low-voltage Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

The 74LVC273 has eight edge-triggered, D-type flip-flops with individual D inputs and Q outputs. The common clock (CP) and master reset (MR) inputs load and reset (clear) all flip-flops simultaneously. The state of each D input, one set-up time before the LOW-to-HIGH clock transition, is transferred to the corresponding output (Qn) of the flip-flop.

All outputs will be forced LOW independently of clock or data inputs by a LOW voltage level on the MR input.

The device is useful for applications where the true output only is required and the clock and master reset are common to all storage elements.

QUICK REFERENCE DATA

GND = 0V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5 \text{ ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	Propagation delay CP to Qn; MR to Q _n	C _L = 50pF V _{CC} = 3.3V	6.0 6.0	ns
f _{max}	Maximum clock frequency		230	MHz
C _I	Input capacitance		5.0	pF
C _{PD}	Power dissipation capacitance per flip-flop	$V_I = GND \text{ to } V_{CC}^{-1}$	22	pF

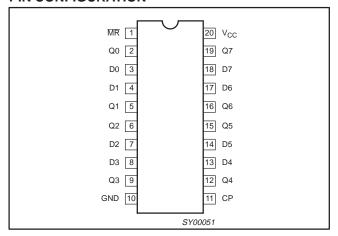
NOTE:

 $\Sigma (C_L \times V_{CC}^2 \times f_0) = \text{sum of the outputs.}$

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic SO	-40°C to +85°C	74LVC273 D	74LVC273 D	SOT163-1
20-Pin Plastic SSOP Type II	-40°C to +85°C	74LVC273 DB	74LVC273 DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC273 PW	74LVC273PW DH	SOT360-1

PIN CONFIGURATION



PIN DESCRIPTION

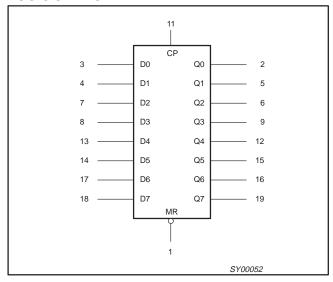
PIN NUMBER	SYMBOL	FUNCTION
1	MR	Master reset input (active LOW)
2, 5, 6, 9, 12, 15, 16, 19	Q0 – Q7	Flip-flop outputs
3, 4, 7, 8, 13, 14, 17, 18	D0 – D7	Data inputs
10	GND	Ground (0V)
11	СР	Clock input (LOW-to-HIGH, edge-triggered)
20	V _{CC}	Positive power supply

C_{PD} is used to determine the dynamic power dissipation (P_D in μ W) P_D = C_{PD} × V_{CC}² x f_i + Σ (C_L × V_{CC}² × f_o) where: f_i = input frequency in MHz; C_L = output load capacity in pF; f_o = output frequency in MHz; V_{CC} = supply voltage in V;

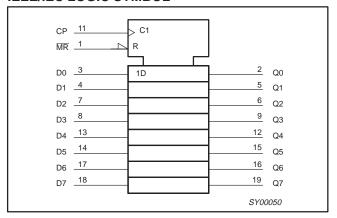
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LOGIC SYMBOL



IEEE/IEC LOGIC SYMBOL



FUNCTION TABLE

OPERATING		INPUTS		OUTPUT
MODES	MR	СР	Dn	Q0 – Q7
Reset (clear)	L	Х	Х	L
Load '1'	Н	1	h	Н
Load '0'	Н	1	I	L

HIGH voltage level HIGH voltage level one set-up time prior to the HIGH-to-LOW CP transition

= LOW voltage level

LOW voltage level one set-up time prior to the HIGH-to-LOW CP transition

LOW-to-HIGH transition

Don't care

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIM	ITS	UNIT
STWIBUL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V	DC supply voltage (for max. speed performance)		2.7	3.6	V
V _{CC}	DC supply voltage (for low-voltage applications)		1.2	3.6	V
V _I	DC Input voltage range		0	5.5	V
V _{I/O}	DC Input voltage range for I/Os		0	V _{CC}	V
V _O	DC output voltage range		0	V _{CC}	V
T _{amb}	Operating free-air temperature range		-40	+85	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7 \text{V}$ $V_{CC} = 2.7 \text{ to } 3.6 \text{V}$	0	20 10	ns/V

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ABSOLUTE MAXIMUM RATINGS¹

In accordance with the Absolute Maximum Rating System (IEC 134)

Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +6.5	V
I _{IK}	DC input diode current	V ₁ < 0	- 50	mA
VI	DC input voltage	Note 2	-0.5 to +5.5	V
I _{OK}	DC output diode current	$V_{O} > V_{CC}$ or $V_{O} < 0$	±50	mA
V _O	DC output voltage	Note 2	–0.5 to V _{CC} +0.5	V
Io	DC output source or sink current	$V_O = 0$ to V_{CC}	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		± 100	mA
T _{stg}	Storage temperature range		-65 to +150	°C
Ртот	Power dissipation per package – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

NOTES

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

			ι			
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -	40°C to	+85°C	UNIT
			MIN	TYP ¹	MAX	1
	LUCI Lovel Innut veltage	V _{CC} = 1.2V	V _{CC}			V
V _{IH}	HIGH level Input voltage	V _{CC} = 2.7 to 3.6V	2.0			1 °
V	LOW level length veltage	V _{CC} = 1.2V			GND	V
V _{IL}	LOW level Input voltage	V _{CC} = 2.7 to 3.6V			0.8	1
		V _{CC} -0.5				
V _{OH}	HICH level output voltage	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -100\mu A$	V _{CC} - 0.2	V _{CC}		V
VOH	HIGH level output voltage	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -12mA$	V _{CC} -0.6			
		V _{CC} - 1.0				
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 12mA$			0.40	
V_{OL}	LOW level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$			0.20	V
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 24$ mA			0.55	
f _l	Input leakage current	$V_{CC} = 3.6V; V_I = 5.5V \text{ or GND}$		±0.1	±5	μΑ
l _{OZ}	3-State output OFF-state current	$V_{CC} = 3.6V$; $V_I = V_{IH}$ or V_{IL} ; $V_O = V_{CC}$ or GND		0.1	±10	μА
Icc	Quiescent supply current	$V_{CC} = 3.6V; V_I = V_{CC} \text{ or GND}; I_O = 0$		0.1	10	μА
ΔI_{CC}	Additional quiescent supply current	$V_{CC} = 2.7V \text{ to } 3.6V; V_I = V_{CC} -0.6V; I_O = 0$		5	500	μΑ

NOTE

^{1.} Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{1.} All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

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AC CHARACTERISTICS

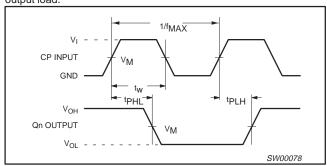
GND = 0V; $t_R = t_F = 2.5 ns$; $C_L = 50 pF$; $R_L = 500 \Omega$; $T_{amb} = -40 ^{\circ} C$ to $+85 ^{\circ} C$.

					LIM	ITS			
SYMBOL	PARAMETER	WAVEFORM	V _{CC}	= 3.3V ±0).3V	١	/ _{CC} = 2.7\	/	UNIT
			MIN	TYP ¹	MAX	MIN	TYP	MAX]
t _{PHL} t _{PLH}	Propagation delay CP to Qn	1		6.0	10.2		6.6	11.2	ns
t _{PHL}	Propagation delay MR to Qn	2		6.3	11.0		7.4	12.0	ns
t _W	Clock pulse width HIGH or LOW	1	4	1.2		5	1.8		ns
t _W	Master reset pulse width LOW	2	4	1.2		5	1.7		ns
t _{rem}	Removal time MR to CP	2	2	-1.0		3	-1.0		ns
t _{su}	Set-up time D _n to CP	3	2	0.7		3	1.0		ns
t _h	Hold time D _n to CP	3	0	-0.6		0	-0.9		ns
f _{max}	Maximum clock pulse frequency	1	125			100			MHz

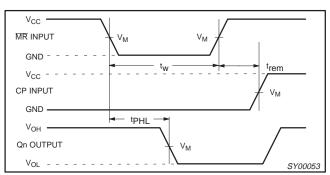
NOTE:

AC WAVEFORMS

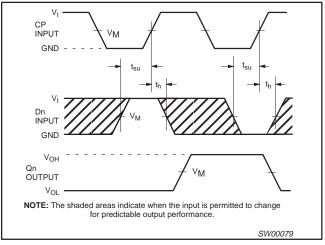
 V_M = 1.5V at $V_{CC} \ge 2.7V.$ V_M = 0.5 V_{CC} at $V_{CC} < 2.7V.$ V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.



Waveform 1. Clock (CP) to output (Qn) propagation delays, the clock pulse width and the maximum clock pulse frequency



Waveform 2. Master reset (MR) pulse width, the master reset to output (Qn) propagation delays and the master reset to clock (CP) removal time



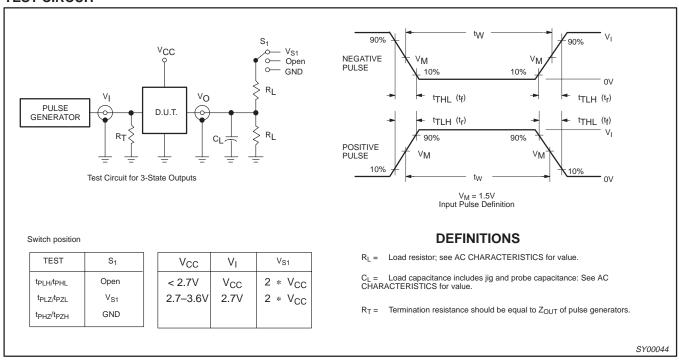
Waveform 3. Data set-up and hold times for the data input (D_n)

^{1.} These typical values are at $V_{CC} = 3.3V$ and $T_{amb} = 25^{\circ}C$.

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TEST CIRCUIT



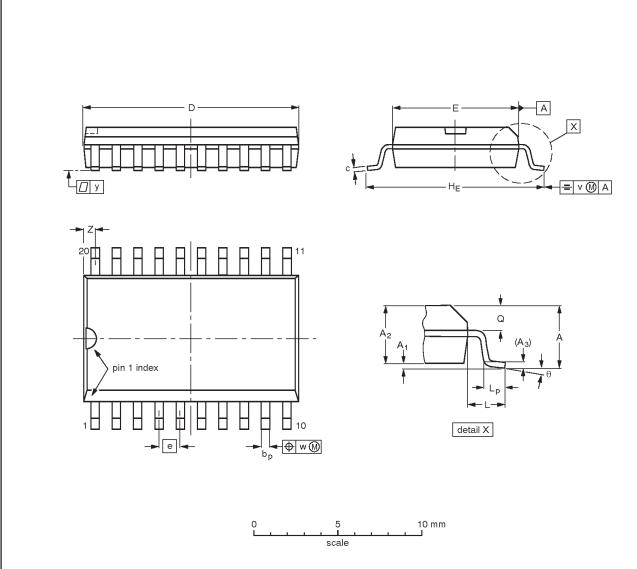
Waveform 4. Load circuitry for switching times

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SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	O	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	٧	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	o°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	PROJECTION	ISSUE DATE		
SOT163-1	075E04	MS-013AC				92-11-17 95-01-24

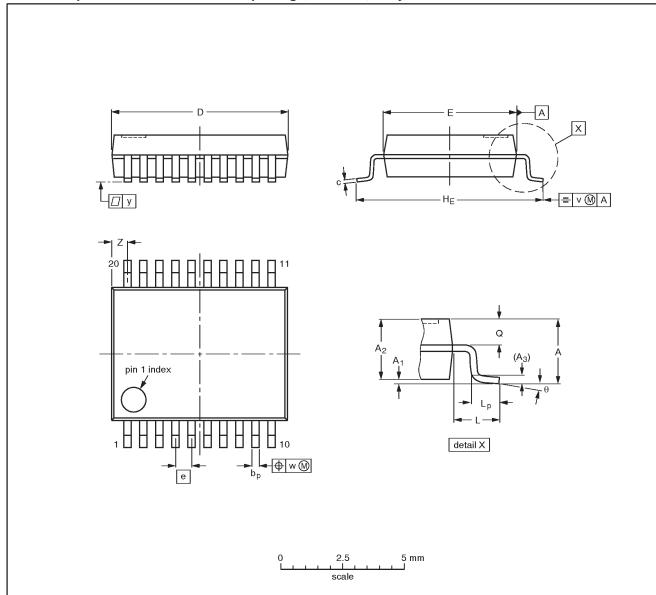
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SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



DIMENSIONS (mm are the original dimensions)

			9			,												
UNIT	A max.	Α1	A ₂	Α3	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

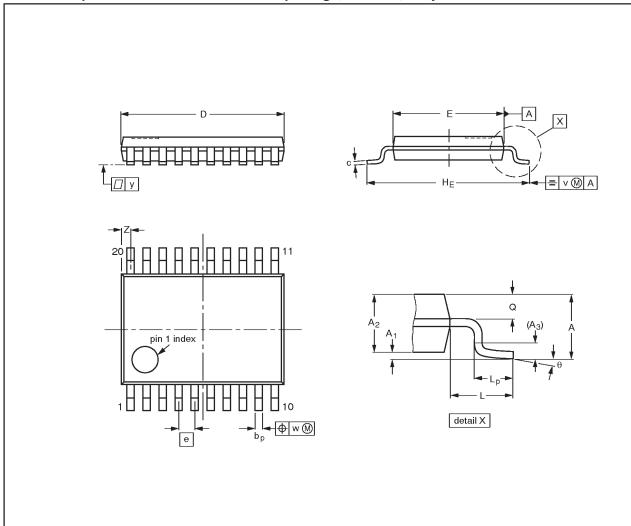
OUTLINE		REFER	RENCES		EUROPEAN	ISSUE DATE	
VERSION	IEC JEDEC EIAJ				PROJECTION	ISSUE DATE	
SOT339-1		MO-150AE				-93-09-08 95-02-04	

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TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



0 2.5 5 mm scale

DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	рb	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1990E DATE	
SOT360-1		MO-153AC				-93-06-16 95-02-04	

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DEFINITIONS							
Data Sheet Identification	Product Status	Definition					
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.					
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